

Improved Device for Drying Semiconductor Substrates

Summary

The object of the invention is a device for use in drying disc-shaped semiconductor substrates.

5 Background of the Invention

The invention relates to a device being used to treat semiconductor wafers, in which the latter are immersed for some time in a bath containing a liquid and are then taken therefrom so slowly that practically the whole quantity of liquid remains in the bath.

Prior Art / Problems

- 10 A method of this kind may be used, for example, in the manufacture of electric circuits on all kinds of substrates, such as, for example, integrated circuits on semiconductor wafers (for example of silicon), drives for liquid crystal displays on transparent plates of glass or quartz or circuits on plates of synthetic material (circuit boards). The method may also be used in the manufacture of shadow masks for television picture
- 15 tubes or in the manufacture of CD or VLP records. In all these cases, the substrates are immersed many times for some time in a bath containing a liquid, for example in galvanic baths for deposition of metals, in etching baths for etching patterns into metal layers or into semiconductor material, in development baths for developing exposed photo lacquer layers and in rinsing baths for cleaning the substrates. After treatment
- 20 in the liquid baths, the substrates are taken from the liquid and are dried. The substrates can be taken from the liquid in that they are lifted or withdrawn from the liquid, but of course also in that the liquid is caused to flow out of the bath.

- While being taken from the bath the semiconductor wafer reside on a device is used to hold the semiconductor wafer in place. During this process, the problem can arise
- 25 that residues of liquid remain at the edge of the substrate. This can lead to unwanted particles on the edge of the substrate, which are later on effecting the quality of the semiconductor wafer.

The physical effect utilized thereby are described in CN1045539 A (EP 03 855 36 A1), as is an apparatus which is to some extent suitable for conduction of the method.

A device and a method to improve the quality of cleaning in respect to remaining particles of the semiconductor wafer is given in DE 10 2014 207 266 A1. However,
5 using this there are still particles left that reduce the quality of the semiconductor wafers.

It is an object of the present invention to improve said device, and more particularly to show how the number of particles, which are found on the dried substrates, can be reduced by using this device.

10 **Description of the Invention**

Figure 1 shows a device (disc holder) for the present invention.

The device for drying disc-shaped substrates comprises an elongated body (1), which tapers upwards to form a wedge having an angle α between two upper surfaces and the upper edge (2). The upper edge (2) is suitable for a disc-shaped substrate to be
15 supported on.

L1 is the height of the wedge and L2 is the length of the support part.

The upper surface (3) comprises a groove (4) having an increasing groove depth with increasing distance from the upper edge (2). Preferably, the groove is a triangular groove.

20 Preferably, the wedge opening angle α is larger than 30° and smaller than 90° , preferably more than 50° and less than 70° .

Preferably, the material used for the device comprises ceramic filled polyetheretherketone (CFM PEEK).

Preferably, the curvature radius of the upper edge is not less than 0.1mm and not
25 more than 1mm.

Preferably, the two surface are hydrophobic.

Preferably, the maximum groove depth is not less than 1mm and not more than 5mm.

Preferably, an upper surface (3) comprises not less than 3 grooves (4).

Preferably, the groove (4) has a triangular shape.

- 5 Preferably, the opening angle of the triangular shape of a groove is not less than 80mm and not more than 100mm.

List of reference numerals employed

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| L1 | Height of the wedge formed on top of the elongated body |
| L2 | Height of the support part |
| 1 | Elongated body |
| 2 | Upper edge of the elongated body |
| 3 | Upper Surface |
| 4 | Chamfering diameter of the elongated body. |
| α | Opening angle of the wedge, angle between the upper two surfaces and an upper edge |

Claims

1. Device for drying disc-shaped substrates comprising
an elongated body (1),
which tapers upwards to form a wedge having an angle α between two upper
5 surfaces and the upper edge (2)
wherein the upper edge (2) is suitable for a disc-shaped substrate to be supported
on, characterized in that
an upper surface (3) comprises a groove (4) having an increasing groove depth
with increasing distance from the upper edge (2).
- 10 2. Device according to claim 1, characterized in that
the wedge opening angle α is larger than 30° and smaller than 90°, preferably
larger than 50° and smaller than 70°.
3. Device according to claim 1 or claim 2, characterized in that
the material used for the device comprises ceramic filled polyetheretherketone
15 (CFM PEEK).
4. Device according to claim 1 to claim 3, characterized in that
the curvature radius is not less than 0.1 mm and not more than 1mm.
5. Device according to claim 1 to claim 4, characterized in that
the maximum groove depth is not less than 1 mm and not more than 5mm.
- 20 6. Device according to claim 1 to claim 5, characterized in that
an upper surface (3) comprises not less than 3 grooves (4).
7. Device according to claim 1 to claim 6, characterized in that
the groove (4) has a triangular shape.
8. Device according to claim 7, characterized in that
25 the opening angle of the triangular shape of a groove is not less than 80° and not
more than 100°.